

MTS-3267US



PATENT

#64

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yashushi Ayaki : Art Unit: 2615
Serial No.: 09/891,626 : Examiner:
Filed: June 26, 2001 :
FOR: RECORDING AND :
REPRODUCTION APPARATUS,
MEDIUM AND INFORMATION
ASSEMBLY

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents

Washington, D.C. 20231

S I R :

Pursuant to 37 C.F.R. §§ 1.97 and 1.98 and to the duty of disclosure set forth in 37 C.F.R. § 1.56, the Examiner in charge of the above-identified application is requested to consider and make of record the references listed on the PTO 1449 (R&P) submitted herewith. A copy of each of the listed references is also enclosed.

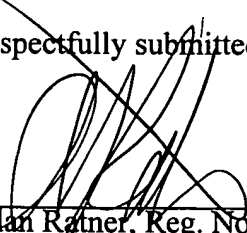
Although the information submitted herewith may be "material" to the Examiner's consideration of the subject application, this submission is not intended to constitute an admission that such information is "prior art" as to the claimed invention.

In accordance with 37 C.F.R. § 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

Japanese References 3-87945, 62-231351, 4-17160, 7-182288 and 5-53895 are not in the English language, but English abstracts thereof are attached to the copies of the references submitted herewith.

No first Official Action has yet been received and it is presumed that none has yet been mailed. No fee or certification is required. 37 C.F.R. § 1.97(b).

Respectfully submitted,



Allan Ratner, Reg. No. 19,717
Attorney for Applicant

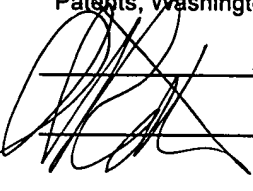
Encls.: PTO Form 1449,
Copy of (5) References

Dated: October 15, 2001

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The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 18-0350 of any fees associated with this communication.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on:



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